

23-FEB-15 Rev.A

Micro USB2.0 Receptacle 5Pos Water Proof

- 1. Introduction
- 1.1 Testing was performed on the Receptacle for Micro USB2.0 Receptacle 5Pos Water Proof Connector to determine if it meets the requirements of Product Specification, 108-61243 Rev.A1.
- 1.2 Scope

This report covers the electrical, mechanical and environmental performance requirements of the Receptacle for Micro USB2.0 5Pos Water Proof Connector.

The qualification testing was performed between 09 JUN, 2014 and 30 JUN, 2014.

1.3 Conclusion

The Receptacle for Micro USB2.0 5Pos Water Proof Connector meets the electrical, mechanical and environmental performance requirements of Product Specification, 108-61243 Rev.A1.

1.4 Test Samples

The test samples were randomly selected from normal current production lots, and the following

Part numbers were used for test:

Description	Part Number
Receptacle For Micro USB2.0 5Pos Water Proof Connector, B-Type	2108877
Plug For 5Pos , B-Type	-
Sealing	2108883

Tyco Electronics AMP Korea Ltd.

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2. Test Contents

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Para.	Test Items	Requirements	Procedures
3.5.11	Shock	No physical damage. No change to performance. No discontinuity greater than 1.0 microsecond.	Apply 3 successive shocks in each direction along the 3 mutually perpendicular axes(total 18 shocks) Pulse shape=half sine Peak acceleration=490m/s2(50G) Duration of pulse=11ms
3.5.12	Reverse Mating Strength	50N Min.	Apply a force to the connector in reverse mating condition at a rate of 12.5mm per minute maximum until the breakdown occurs or connector is inserted.
3.5.13	Soldering Strength	80N Min.	Apply a force to the connector in each parallel direction(X & Y) with PCB at a rate of 12.5mm per minute maximum until the breakdown of connector or soldering parts occurs. (Fig.5)
3.5.14	Compulsory Insertion Strength	250N Min.	Apply a force to the mated connector at a rate of 12.5mm per minute maximum until the breakdown occurs.
3.5.15	Swing wrenching durability with 1kgf (Set condition test)	No physical damage and shall meet requirements of subsequent tests.	Apply 1kgf, 10,000 cycles of swing wrenching force in each direction (horizontal & vertical) at a rate of 100mm per minute maximum. (Fig.6)
3.5.16	Swing wrenching durability with 10kgf (Set condition test)	No physical damage and shall meet requirements of subsequent tests.	Apply 10kgf, 10 cycles of swing wrenching force in each direction (horizontal & vertical) at a rate of 100mm per minute maximum. (Fig.7)
		Environmental Requirement	ts
3.5.17	Dry cold (steady state)	No physical damage and shall meet requirement of subsequent test.	-40°C±3°C for 96 hours Recovery period 2 hours at ambient atmosphere. [MIL-STD-202 Method 108]
3.5.18	Dry heat (steady state)	No physical damage and shall meet requirement of subsequent test.	+85°C±2°C for 96 hours Recovery period 2 hours at ambient atmosphere. [MIL-STD-202 Method 108]
Para.	Test Items	Requirements	Procedures
3.5.19	Thermal Shock (change of temperature)	No physical damage and shall meet requirement of subsequent test.	Ta=-40°C for 2 hours; then change of temp.=25°C , 5minute max.; then Tb=+85°C for 2 hours. After 20cycles, cool to ambient for 2 hours.
3.5.20	Damp heat (steady state)	No physical damage and shall meet requirement of subsequent test.	120 hours at Temp. 85°C±2°C, R/H 85±5%; After test, cool to ambient temp. for 2 hours.



Salt spray	No physical damage and shall	48 hours spray, At temp. 35±2 °C				
	meet requirement of	R/H 90~95%, Salt Na-CI mist 5%				
	subsequent test.	After test wash parts and return to room				
		ambient for 2 hours. [EIA-364-26B]				
Solder-ability	Solderable area shall have a	255°C±5°C of lead free soler pot				
	minimum of 95% solder	temperature, for 5+0/-0.5 seconds.				
	coverage.					
Resistance to Reflow	No mechanical damage	Temperature profile ; as shown in Fig.3				
Heat	allowed.	24hours at temp. 85±2 °C, R/H 85±5%.				
		Recovery : 0.5 hours at ambient				
		atmosphere; then apply Reflow 3 times.				
		(Fig.3)				
Waterproof IPX-5	Protected against water jets	Water projected at all angles through a				
		6.3mm nozzle at a flow rate of 12.5				
		liters/min at a pressure of 30kN/m2 for 3				
		minutes from a distance of 3 meters.(Fig.8)				
Waterproof IPX-8	Protected against water	Submersion for 30 minutes at a depth of				
	submersion	1.5 meters. (Fig.8)				
	Salt spray Solder-ability Resistance to Reflow Heat Waterproof IPX-5 Waterproof IPX-8	Salt sprayNo physical damage and shall meet requirement of subsequent test.Solder-abilitySolderable area shall have a minimum of 95% solder coverage.Resistance to Reflow HeatNo mechanical damage allowed.Waterproof IPX-5Protected against water jetsWaterproof IPX-8Protected against water submersion				

Fig. 2 (End)



3. Product Qualification Test Sequence

	Test Group															
Para.	Test Examination	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
								Test S	Sequer	nce (a)						
3.5.1	Examination of Product	1,11	1	1	1	1,9	1,5	1,3	1,5	1,5	1,9	1,7	1,5	1,7	1,6	1,6
3.5.2	Contactresistance (Low Level)	2,8				2,6	2,4		2,4	2,4			2,4	2,4	3	3
3.5.3	Insulation resistance										2,5	2,5				
3.5.4	Dielectric withstanding Voltage										3,6	3,6				
3.5.5	Temperature Rise												3			
3.5.6	Mating force	3,7														
3.5.7	Un-mating force	4,6														
3.5.8	Durability	5														
3.5.9	Vibration					3										
3.5.10	Random Vibration					4										
3.5.11	Shock					5										
3.5.12	Reverse Mating Strength		2													
3.5.13	Soldering Strength			2												
3.5.14	Compulsory Insertion Strength				2											
3.5.15	Swing wrenching durability with 1kgf														2	
3.5.16	Swing wrenching durability with 10kgf															2
3.5.17	Dry cold (steady state)								3							
3.5.18	Dry heat (steady state)									3						
3.5.19	Thermal Shock										4					
3.5.20	Damp heat(steady state)											4				
3.5.21	Salt spray						3									
3.5.22	Solder-ability							2								
3.5.23	Resistance to Reflow Heat													3		
3.5.24	Waterproof IPX-5	9				7					7			5	4	4
3.5.25	Waterproof IPX-8	10				8					8			6	5	5

(a) Numbers indicate sequence in which the tests are performed.

Fig. 3 (End)



4. Test Results

Crawn	Test liem		Canditian			Test R	esult		Deswinement	Conclusion	
Group	rest tiem		Condition		Max Min		Ave	Unit	Requirement	Conclusion	
	Examination of Product	3	initial		No ph	ysical dam	age	N/A	No abnormalities	Meet spec	
	Contact resistance (Low Level)	3	initial	2	9.00	23.80	26.55	mΩ	50mΩ Max.	Meet spec	
	Mating force	3	initial	1	1.50	10.80	11.07	Ν	2-25N	Meet spec	
	Un-mating force	3	initial	1	3.20	11.20	12.07	Ν	8-20N	Meet spec	
2	Durability	3	final		No physical damage			N/A	No abnormalities	Meet spec	
1	Un-mating force	3	final	1	4.60	13.20	13.83	N	2-25N	Meet spec	
	Mating force	3	final	1	7.70	12.80	16.00	N	8-20N	Meet spec	
	Contact resistance (Low Level), ΔR	3	final	2	2.30	-2.90	-0.02	mΩ	ΔR: +/-10mΩ Max.	Meet spec	
	Waterproof IPX-5	3	final		N	o Leakage		/	No abnormalities	Meet spec	
	Waterproof IPX-8	3	final		N	o Leakage		/	No abnormalities	Meet spec	
	Examination of Product	3	final		No ph	ysical damage		N/A	No abnormalities	Meet spec	
	Examination of Product	3	initial		No ph	physical damage		N/A	No abnormalities	Meet spec	
2	Reverse Mating Strength	3	final	2	25.5	177.6	207.7	N	50N Min.	Meet spec	
	Examination of Product	3	initial	No ph		No physical damage		N/A	No abnormalities	Meet spec	
3		3 fi	final	-X	>4501	N still no pe	eling off		001114		
	Soldering Strength	3	final	-Y	300.7	279.1	287.5	N	80N Min.	Meet spec	
	Examination of Product	3	initial		No physical damage		N/A	No abnormalities	Meet spec		
4	Compulsory Insertion Strength	3	final	>4	415.5	>449.0	>438.4	N	250N Min.	Meet spec	
	Examination of Product	3	initial		No ph	ysical dam	age	N/A	No abnormalities	Meet spec	
	Contact resistance (Low Level)	3	initial	3	0.77	23.22	26.11	mΩ	50mΩ Max.	Meet spec	
	Vibration	3	final	No	discontii micros	nuity greater econd occu	than 1.0 rred	N/A	No abnormalities	Meet spec	
5	Random Vibration	3	final	No	discontii micros	nuity greater econd occu	than 1.0 rred	N/A	No abnormalities	Meet spec	
	Shock	3	final	No	discontii micros	nuity greater econd occu	than 1.0 rred	N/A	No abnormalities	Meet spec	
	Contact resistance (Low Level), ΔR	3	final	:	3.45	-5.04	-0.25	mΩ	ΔR: +/-10mΩ Max.	Meet spec	
•			Fig.	4 (to	be cor	ntinued)			•		



Qualification Test Report

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0	Test liese	N	O and it is a		Test I	Result	Deguinement	Conclusion	
Group	rest tiem		Condition	Max	Min	Ave	Unit	Requirement	Conclusion
	Waterproof IPX-5	3	final	1	No Leakage		/	No abnormalities	Meet spec
5	Waterproof IPX-8	3	final	1	No Leakage	Э	/	No abnormalities	Meet spec
	Examination of Product	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Examination of Product	3	initial	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Contact resistance (Low Level)	3	initial	27.24	21.98	24.97	mΩ	50mΩ Max.	Meet spec
6	Salt spray	3	final	No p	hysical dan	nage	N/A	No abnormalities	Meet spec
	Contact resistance (Low Level), ΔR	3	final	3.67	-3.57	0.23	mΩ	ΔR: +/-10mΩ Max.	Meet spec
	Examination of Product	3	final	No p	hysical dan	nage	N/A	No abnormalities	Meet spec
	Examination of Product	3	initial	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
7	Solder-ability	3	final	>95% S	oldering C	overage	N/A	No abnormalities	Meet spec
	Examination of Product	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet Spec
	Examination of Product	3	initial	No p	hysical dar	nage	N/A	No abnormalities	Meet Spec
	Contact resistance (Low Level)	3	initial	26.77	26.77 23.51 25		mΩ	50mΩ Max.	Meet Spec
8	Dry cold (steady state)	3	final	No p	hysical dar	nage		No abnormalities	Meet Spec
	Contact resistance (Low Level), ΔR	3	final	5.41	5.41 -1.83		mΩ	ΔR: +/-10mΩ Max.	Meet Spec
	Examination of Product	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Examination of Product	3	initial	No p	hysical dar	nage	N/A	No abnormalities	Meet Spec
	Contact resistance (Low Level)	3	initial	26.88	23.56	25.34	mΩ	50mΩ Max.	Meet Spec
9	Dry heat (steady state)	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet Spec
	Contact resistance (Low Level), ΔR	3	final	6.35	-2.81	0.61	mΩ	ΔR: +/-10mΩ Max.	Meet Spec
	Examination of Product	3	final	No physical damage			N/A	No abnormalities	Meet spec
	Examination of Product	3	initial	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
10	Insulation resistance	3	initial	6.9	1.98	3.81	10 ¹⁰ Ω	1000MΩ Min.	Meet spec
10	Dielectric withstanding Voltage	3	initial	500VAC Un-mating 700VAC Mating	No flas g brea No flas	hover, No kdown hover, No	N/A N/A	No abnormalities No abnormalities	Meet Spec Meet Spec
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Fig. 4 (to be continued)



Qualification Test Report

	Test Item		Condition		Test I	Result		Canalusian	
Group		N		Max	Min	Ave	Unit	Requirement	Conclusion
	Thermal Shock	3	final	No p	physical damage		N/A	No abnormalities	Meet Spec
	Insulation resistance	3	final	5.61	1.02	2.77	10 ¹⁰ Ω	100MΩ Min.	Meet Spec
	Dielectric withstanding	2	initial	500VAC Un-mating	No fla g No bre	shover , eakdown	N/A	No abnormalities	Meet Spec
10	Voltage	3	miliai	700VAC Mating	No fla No bre	shover , eakdown	N/A	No abnormalities	Meet Spec
	Waterproof IPX-5	3	final	1	No Leakag	Э	/	No abnormalities	Meet spec
	Waterproof IPX-8	3	final	1	No Leakag	Э	/	No abnormalities	Meet spec
	Examination of Product	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Examination of Product	3	initial	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Insulation resistance	3	initial	5.97	2.98	2.98 4.77		1000MΩ Min.	Meet spec
	Dielectric withstanding Voltage	з	initial	500VAC No flashover , Un-mating No breakdown			N/A	No abnormalities	Meet Spec
		5	initiai	700VAC Mating	No fla No bre	shover , eakdown	N/A	No abnormalities	Meet Spec
11	Damp heat(steady state)	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Insulation resistance	3	final	4.21	1.04	1.99	10 ¹⁰ Ω	100MΩ Min.	Meet spec
	Dielectric withstanding	2	initial	500VAC Un-mating	500VAC No flashover , Un-mating No breakdown		N/A	No abnormalities	Meet Spec
	Voltage	5	minai	700VAC No flashover , Mating No breakdown		N/A	No abnormalities	Meet Spec	
	Examination of Product	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Examination of Product	3	initial	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Contact resistance (Low Level)	3	initial	30.50	23.59	25.22	mΩ	50mΩ Max.	Meet spec
12	Temperature Rise	3	final	9.9	6.78	7.95	°C	30°C Max.	Meet spec
	Contact resistance (Low Level), ΔR	3	final	4.44	-4.72	1.20	mΩ	ΔR: +/-10mΩ Max.	Meet spec
	Examination of Product	3	final	No p	hysical dar	nage	N/A	No abnormalities	Meet spec

Fig. 4 (to be continued)



Qualification Test Report

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Group		IN	Condition	Ma	х	Min	Ave	Unit	Requirement	Conclusion
	Examination of Product	3	initial	No ph		No physical damage		N/A	No abnormalities	Meet spec
	Contact resistance (Low Level)	3	initial	27.6	63	22.34	22.34 26.08		50mΩ Max.	Meet spec
	Resistance to Reflow Heat	3	final	I	No p	hysical dar	nage	N/A	No abnormalities	Meet spec
13	Contact resistance (Low Level), ΔR	3	initial	2.8	4	-3.27 -1.27		mΩ	50mΩ Max.	Meet spec
	Waterproof IPX-5	3	final		1	No Leakage	Э	/	No abnormalities	Meet spec
	Waterproof IPX-8	3	final		١	No Leakage	e	/	No abnormalities	Meet spec
	Examination of Product	3	final	I	No p	hysical dar	nage	N/A	No abnormalities	Meet Spec
	Examination of Product	3	initial	No physical damage				N/A	No abnormalities	Meet spec
	Swing wrenching durability with 1kgf	3	final	-H -V	-H Rec. No damage on Both horizontal and -V Vertical axes			N/A	No abnormalities	Meet Spec
14	Contact resistance (Low Level)	3	final	27.	27.8 20.6 25.7		25.79	mΩ	50mΩ Max.	Meet Spec
	Waterproof IPX-5	3	final		1	No Leakage	e	/	No abnormalities	Meet spec
	Waterproof IPX-8	3	final		١	No Leakage	Э	/	No abnormalities	Meet spec
	Examination of Product	3	final	I	No p	hysical dar	nage	N/A	No abnormalities	Meet Spec
	Examination of Product	3	final		No p	hysical dar	nage	N/A	No abnormalities	Meet spec
	Swing wrenching durability with 10kgf	3	final	-H -V	-H Rec. No damage on Both horizontal and -V Vertical axes		N/A	No abnormalities	Meet Spec	
15	Contact resistance (Low Level)	3	final	24.	24.4 20.4		23.13	mΩ	50mΩ Max.	Meet Spec
	Waterproof IPX-5	3	final		١	No Leakage	Э	/	No abnormalities	Meet spec
	Waterproof IPX-8	3	final		١	No Leakage	Э	/	No abnormalities	Meet spec
	Examination of Product	3	final		No p	hysical dar	nage	N/A	No abnormalities	Meet Spec

Fig. 4 (End)